

Method of Processing a Wafer

Abstract

The invention relates to a method of processing a wafer (W), having on one side (1) a device area (2) with a plurality of devices (27). The method comprises providing a protective film (4) and applying the protective film (4) to the one side (1) of the wafer (W) or to the side (6) of the wafer (W) being opposite to the one side (1), so that at least a central area of a front surface (4a) of the protective film (4) is in direct contact with the one side (1) of the wafer (W) or the side (6) of the wafer (W) being opposite to the one side (1). The method further comprises attaching the protective film (4) to the one side (1) of the wafer (W) or to the side (6) of the wafer (W) being opposite to the one side (1), so that at least a part of a peripheral portion of the protective film (4) is attached to at least a part of a lateral edge (5) of the wafer (W) along the entire circumference of the wafer (W). The lateral edge (5) of the wafer (W) extends from the one side (1) of the wafer (W) to the side (6) of the wafer (W) being opposite to the one side (1). Moreover, the method comprises processing the one side (1) of the wafer (W) and/or the side (6) of the wafer (W) being opposite to the one side (1).

[Figure 7]